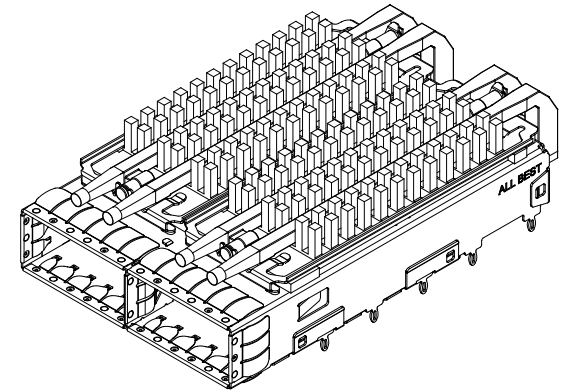
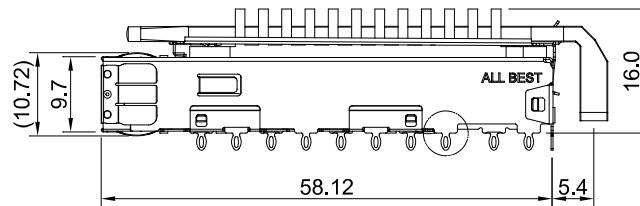
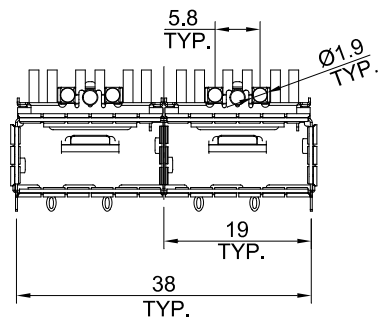


DETAIL A
SCALE 5 : 1



MATERIAL
 CAGE: NICKEL SILVER
 HEAT SINK: ALUMINUM
 LIGHT PIPE CLIP: STAINLESS STEEL
 EMI SPRING: STAINLESS STEEL
 LIGHT PIPE: PC

FINISH
 HEAT SINK: ANODE PROCESS



TITLE: QSFP+ 1X2 Cage Assbmbly w/ Light Pipe & Heat Sink

DWG#: R-OR-Q2-4CME4

SHEET: 1/4
 REV. C

UNIT: mm
 SCALE: A4 1:1

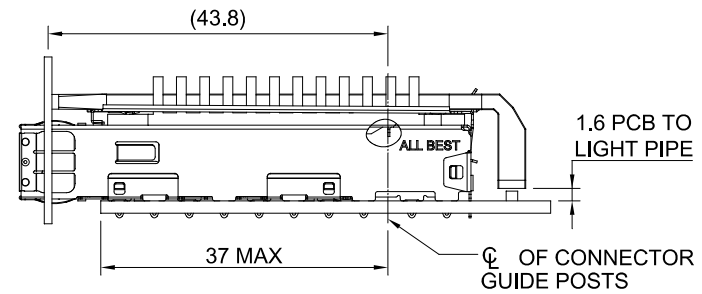
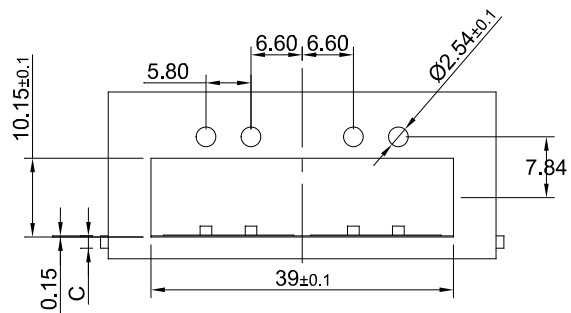
FINISH: CHECKED: Gary Kang

THIRD ANGLE PROJECTION

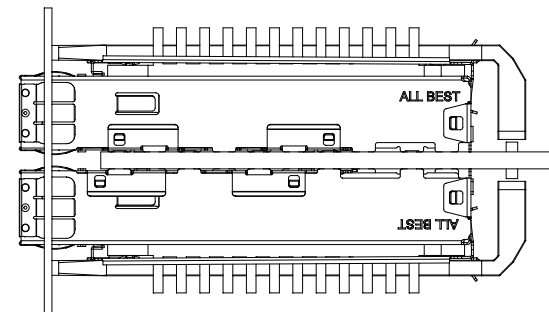
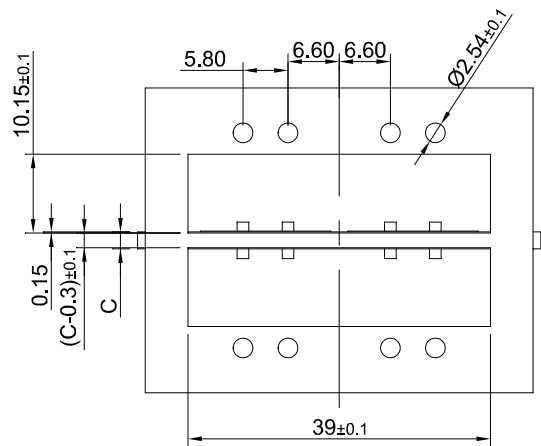
MATERIAL: RoHS Compliant
 APPROVED: George Yang

TOLERANCE: Angle: ± 1°
 X, ± 0.25 .X ± 0.20 .XX ± 0.15

DRAWN: Boris
 DATE: 04/18/2016


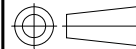


ONE SIDED CONFIGURATION



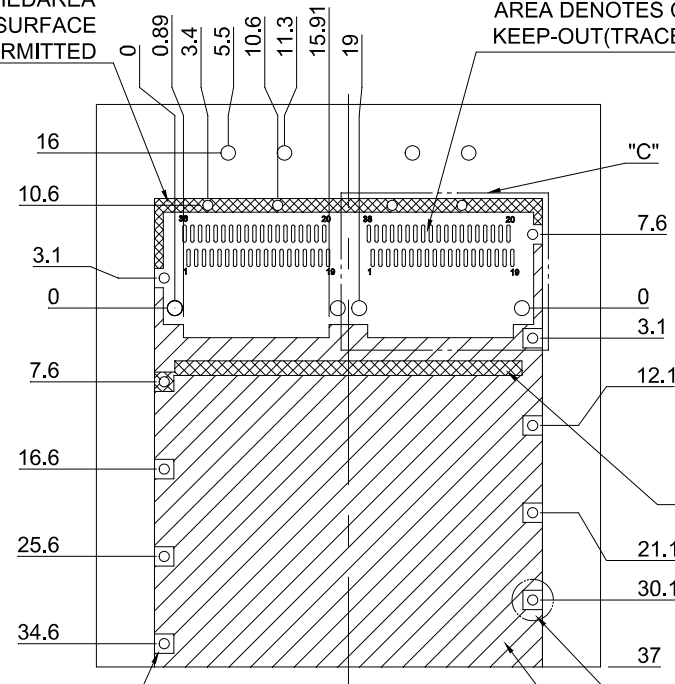
BELLY TO BELLY CONFIGURATION

C=THICKNESS OF PC BOARD
 SINGLE SIDED=1.6MM(MIN)
 DOUBLE SIDE=2.2MM(MIN)

 <p>ALL BEST ELECTRONICS CO., LTD.</p>	TITLE: QSFP+ 1X2 Cage Assmbly w/ Light Pipe & Heat Sink		SHEET: 2/4	REV. C
	DWG#: R-OR-Q2-4CME4		CHECKED: Gary Kang	
	UNIT: mm	SCALE: A4 1:1	FINISH:	APPROVED: George Yang
	TOLERANCE: Angle: ± 1° X.± 0.15 .X± 0.10 .XX± 0.05		MATERIAL: RoHS Compliant	DATE: 04/18/2016
 THIRD ANGLE PROJECTION		DRAWN: Boris		

CROSS HATCHED AREA DENOTES WHERE SURFACE TRACES ARE PERMITTED

AREA DENOTES COMPONENT KEEP-OUT (TRACES ALLOWED)

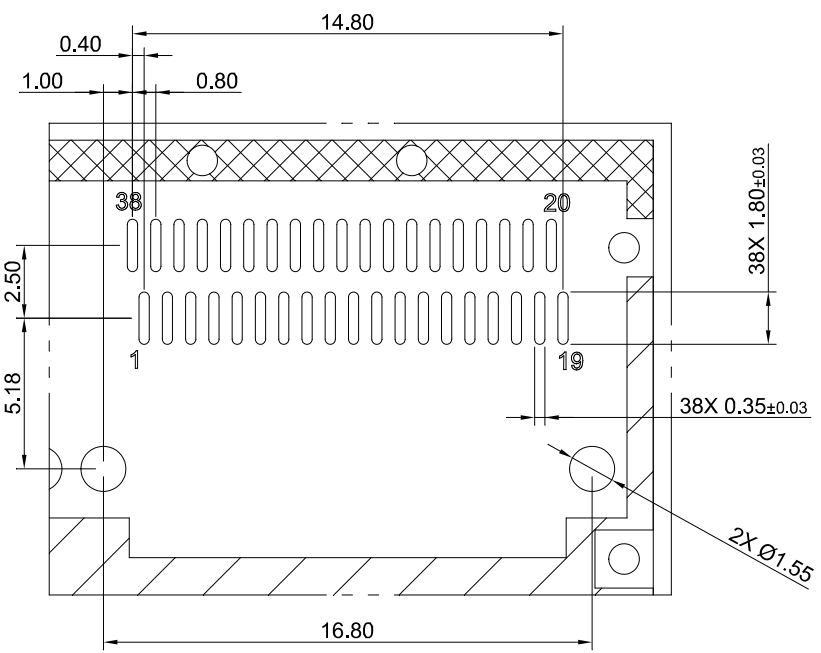


CROSS HATCHED AREA DENOTES EMI GROUNDING PAD (MUST BE CONNECTED TO CHASSIS GROUND)

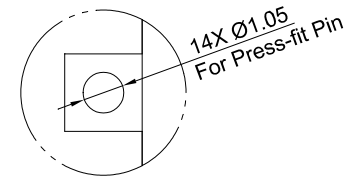
HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

PADS AND VIAS GO TO CHASSIS GROUND (RECOMMEND PADS TO BE 2.00mm SQUARE)

SINGLE SIDE PCB LAYOUT
MINIMUM PCB THICKNESS OF 1.6 MM
TOLERANCE: ± 0.05



DETAIL C
SCALE 3:1



DETAIL B
SCALE 4:1

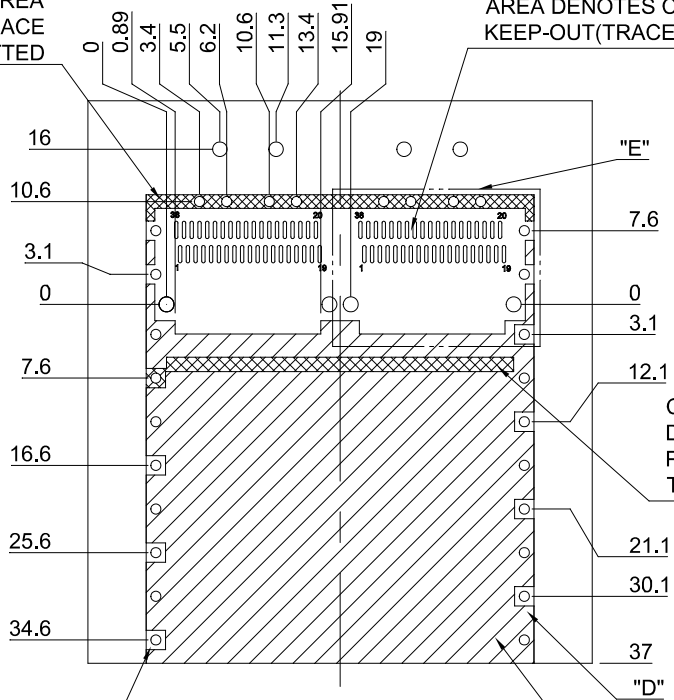


ALL BEST
ELECTRONICS
CO., LTD.

TITLE: QSFP+ 1X2 Cage Assbmbly w/ Light Pipe & Heat Sink			
DWG#: R-OR-Q2-4CME4		SHEET: 3/4	REV. C
UNIT: mm	SCALE: A4 5:4	FINISH:	CHECKED: Gary Kang
THIRD ANGLE PROJECTION		MATERIAL: RoHS Compliant	APPROVED: George Yang
TOLERANCE: Angle: $\pm 1^\circ$ X: ± 0.15 .X: ± 0.10 .XX: ± 0.05		DRAWN: Boris	DATE: 04/18/2016

CROSS HATCHED AREA DENOTES WHERE SURFACE TRACES ARE PERMITTED

AREA DENOTES COMPONENT KEEP-OUT (TRACES ALLOWED)

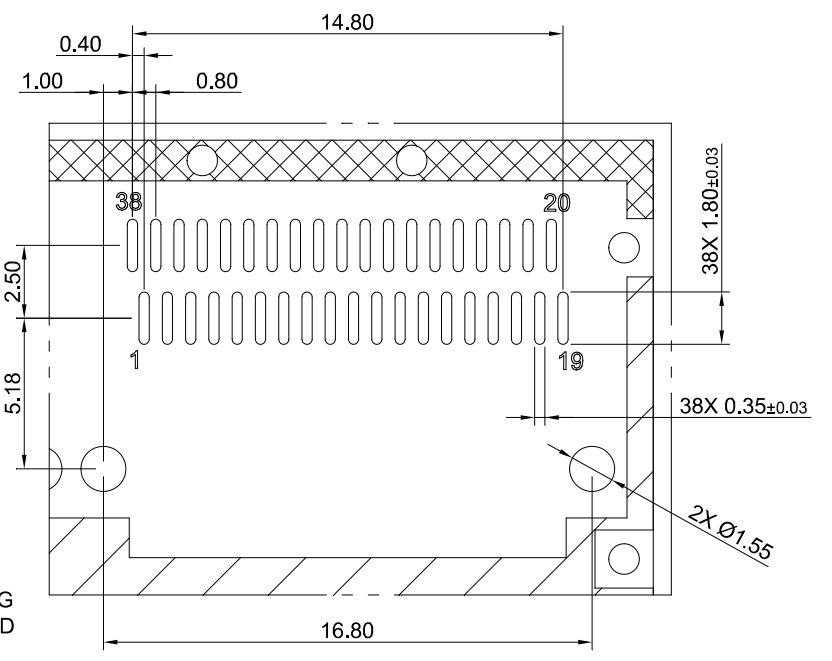


CROSS HATCHED AREA DENOTES EMI GROUNDING PAD (MUST BE CONNECTED TO CHASSIS GROUND)

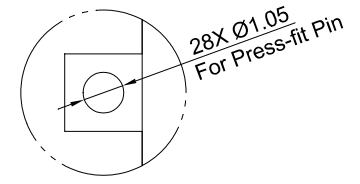
PADS AND VIAS GO TO CHASSIS GROUND (RECOMMEND PADS TO BE 2.00mm SQUARE)

DOUBLE SIDE PCB LAYOUT
MINIMUM PCB THICKNESS OF 2.2 MM
TOLERANCE: ±0.05

HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)



DETAIL E
SCALE 3:1



DETAIL D
SCALE 4:1



ALL BEST
ELECTRONICS
CO., LTD.

TITLE: QSFP+ 1X2 Cage Assbmbly w/ Light Pipe & Heat Sink			
DWG#: R-OR-Q2-4CME4		SHEET: 4/4	REV. C
UNIT: mm	SCALE: A4 5:4	FINISH:	CHECKED: Gary Kang
THIRD ANGLE PROJECTION		MATERIAL: RoHS Compliant	APPROVED: George Yang
TOLERANCE: Angle: ± 1° X ± 0.15 .X ± 0.10 .XX ± 0.05		DRAWN: Boris	DATE: 04/18/2016